

ABSTRACT
ENCAPSULATED SURFACE ACOUSTIC WAVE COMPONENT AND
METHOD OF COLLECTIVE FABRICATION

The invention relates to a new type of encapsulated surface
5 acoustic wave component and to a method for the batch production of such
components.

The component comprises a surface acoustic wave device on the
surface of a substrate. The encapsulation package furthermore comprises
the substrate, a first layer located on the substrate and hollowed out locally
10 at least at the level of the active surface of the surface acoustic wave device,
a printed circuit covering entire first layer and conductive via holes going
through the unit formed by the first layer and the printed circuit so as to
provide for the electrical connection of the surface acoustic wave device from
the exterior.

15 Figure 3



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